

## Single N-Channel MOSFET

### DESCRIPTION

SMC4628M is the N-Channel enhancement mode power field effect transistors are using trench DMOS technology. This advanced technology has been especially tailored to minimize on-state resistance, provide superior, fast switching performance. These devices are well suited for high efficiency fast switching applications.

### PART NUMBER INFORMATION

**SMC 4628 M - TR G**  
 a b c d e

- a : Company name.
- b : Product Serial number.
- c : Package code M:SOP-8
- d : Handling code TR:Tape&Reel
- e : Green produce code G:RoHS Compliant

### FEATURES

**$V_{DS}=60V, I_D=7A$**

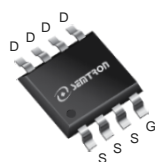
$R_{DS(ON)}=30m\Omega(Typ.)@V_{GS}=10V$

$R_{DS(ON)}=37m\Omega(Typ.)@V_{GS}=4.5V$

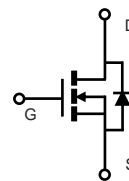
- ◆Fast switch
- ◆Improved dv/dt capability
- ◆High power and current handling capability

### APPLICATIONS

- ◆LED Application
- ◆Power Management
- ◆Motor Drive



SOP-8



### ABSOLUTE MAXIMUM RATINGS ( $T_A = 25^\circ C$ Unless otherwise noted)

| Symbol    | Parameter  | Rating           | Units      |
|-----------|--|------------------|------------|
| $V_{DSS}$ | Drain-Source Voltage                                 | 60               | V          |
| $V_{GSS}$ | Gate-Source Voltage                                  | $\pm 20$         | V          |
| $I_D$     | Continuous Drain Current                             | $T_A=25^\circ C$ | 7          |
|           |  | $T_A=70^\circ C$ | 5.6        |
| $I_{DM}$  | Pulsed Drain Current <sup>B</sup>                    | 28               | A          |
| $I_{AS}$  | Avalanche Current <sup>B</sup>                       | 18               | A          |
| $E_{AS}$  | Single Pulse Avalanche energy $L=0.1mH$ <sup>B</sup> | 16               | mJ         |
| $P_D$     | Power Dissipation <sup>A</sup>                       | $T_A=25^\circ C$ | 3.1        |
|           |  | $T_A=70^\circ C$ | 2          |
| $T_J$     | Operation Junction Temperature                       | -55/150          | $^\circ C$ |
| $T_{STG}$ | Storage Temperature Range                            | -55/150          | $^\circ C$ |

### THERMAL RESISTANCE

| Symbol          | Parameter  | Typ          | Max | Units        |
|-----------------|--|--------------|-----|--------------|
| $R_{\theta JA}$ | Thermal Resistance Junction to Ambient <sup>A</sup>  | $t \leq 10s$ | 40  | $^\circ C/W$ |
|                 | Thermal Resistance Junction to Ambient <sup>AC</sup> | Steady-State | 70  |              |

## ELECTRICAL CHARACTERISTICS ( $T_A = 25^\circ\text{C}$ Unless otherwise noted)

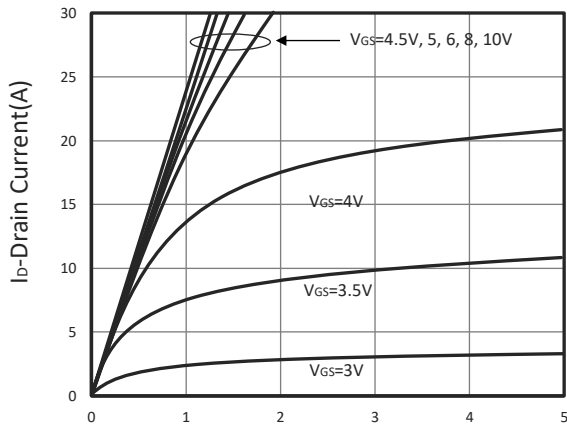
| Symbol   | Parameter                               | Condition  | Min | Typ      | Max       | Unit       |
|--|---|--|-----|----------|-----------|------------|
| <b>Static Parameters</b>                             |   |  |     |          |           |            |
| BV <sub>DSS</sub>                                    | Drain-Source Breakdown Voltage          | V <sub>GS</sub> =0V, I <sub>D</sub> =250 $\mu$ A   | 60  |          |           | V          |
| V <sub>GS(th)</sub>                                  | Gate Threshold Voltage                  | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250 $\mu$ A                                 | 1.2 | 1.8      | 2.5       | V          |
| I <sub>GSS</sub>                                     | Gate Leakage Current                    | V <sub>DS</sub> =0V, V <sub>GS</sub> = $\pm$ 20V   |     |          | $\pm$ 100 | nA         |
| I <sub>DSS</sub>                                     | Zero Gate Voltage Drain Current         | V <sub>DS</sub> =60V, V <sub>GS</sub> =0V, T <sub>J</sub> =25 $^\circ$ C                       |     |          | 1         | $\mu$ A    |
|  |   | V <sub>DS</sub> =48V, V <sub>GS</sub> =0V, T <sub>J</sub> =75 $^\circ$ C                       |     |          | 10        |            |
| R <sub>DS(ON)</sub>                                  | Drain-source On-Resistance <sup>D</sup> | V <sub>GS</sub> =10V, I <sub>D</sub> =7A<br>V <sub>GS</sub> =4.5V, I <sub>D</sub> =5.8A        |     | 31<br>37 | 35<br>45  | m $\Omega$ |
| G <sub>fs</sub>                                      | Forward Transconductance                | V <sub>DS</sub> =10V, I <sub>D</sub> =7A   |     | 6.5      |           | S          |
| <b>Diode Characteristics</b>                         |   |  |     |          |           |            |
| V <sub>SD</sub>                                      | Diode Forward Voltage <sup>D</sup>      | I <sub>S</sub> =1A, V <sub>GS</sub> =0V  |     |          | 1.0       | V          |
| I <sub>S</sub>                                       | Diode Continuous Forward Current        |  |     |          | 3.5       | A          |
| t <sub>rr</sub>                                      | Reverse Recovery Time                   | I <sub>S</sub> =7A, di/dt=100A/ $\mu$ s  |     | 23       |           | ns         |
| Q <sub>rr</sub>                                      | Reverse Recovery Charge                 |  |     |          | 30        |            |
| <b>Dynamic and Switching Parameters <sup>E</sup></b> |   |  |     |          |           |            |
| Q <sub>g</sub>                                       | Total Gate Charge                       | V <sub>DS</sub> =30V, V <sub>GS</sub> =10V, I <sub>D</sub> =7A                                 |     | 12.3     | 16.6      | nC         |
| Q <sub>g</sub>                                       | Total Gate Charge (4.5V)                |  |     | 6        | 8.1       |            |
| Q <sub>gs</sub>                                      | Gate-Source Charge                      |  |     | 2.9      | 3.9       |            |
| Q <sub>gd</sub>                                      | Gate-Drain Charge                       |  |     | 3        | 4.1       |            |
| C <sub>iss</sub>                                     | Input Capacitance                       | V <sub>DS</sub> =30V, V <sub>GS</sub> =0V, f=1MHz  |     | 635      |           | pF         |
| C <sub>oss</sub>                                     | Output Capacitance                      |  |     | 78       |           |            |
| C <sub>rss</sub>                                     | Reverse Transfer Capacitance            |  |     | 40       |           |            |
| R <sub>g</sub>                                       | Gate Resistance                         | V <sub>GS</sub> =0V, V <sub>DS</sub> =0V, F=1MHz   |     | 1.7      |           | $\Omega$   |
| t <sub>d(on)</sub>                                   | Turn-On Time                            | V <sub>DD</sub> =30V, V <sub>GEN</sub> =10V<br>R <sub>G</sub> =6 $\Omega$ , I <sub>D</sub> =1A |     | 8.2      | 16        | nS         |
| t <sub>r</sub>                                       |   |  |     | 9        | 17        |            |
| t <sub>d(off)</sub>                                  | Turn-Off Time                           |  |     | 27       | 51        |            |
| t <sub>f</sub>                                       |   |  |     | 20       | 38        |            |

Note: Absolute maximum ratings are those values beyond which the device could be permanently damaged.

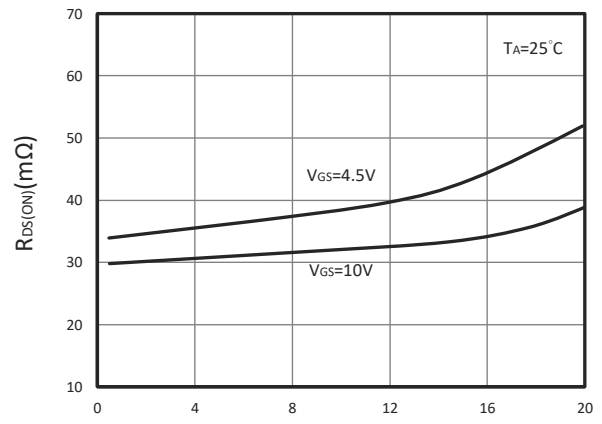
- A. Surface mounted on FR4 board using 1 in<sup>2</sup> pad size.
- B. Pulsed width limited by maximum junction temperature, T<sub>J(MAX)</sub>=150 $^\circ$ C.
- C. Using  $\leq$  10s junction-to-ambient thermal resistance is base on T<sub>J(MAX)</sub>=150 $^\circ$ C.
- D. Pulse test width  $\leq$ 300 $\mu$ s and duty cycle  $\leq$  2%.
- E. Guaranteed by design, not subject to production testing.

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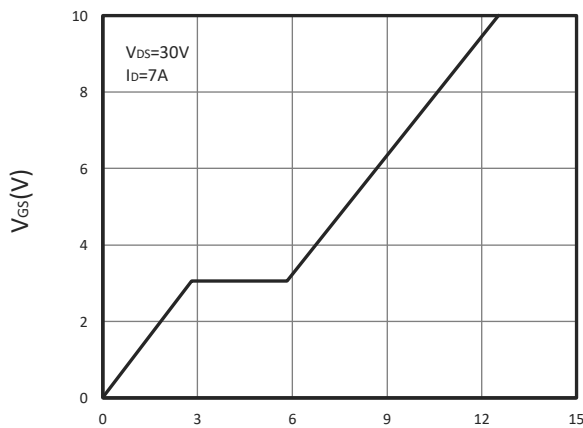
## TYPICAL CHARACTERISTICS



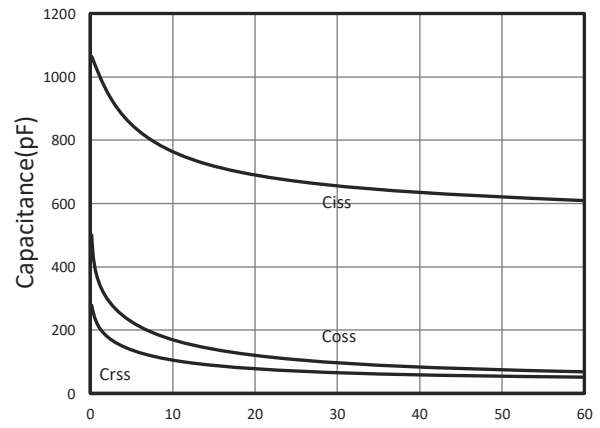
VDS-Drain Source Voltage (V)  
**Output Characteristics**



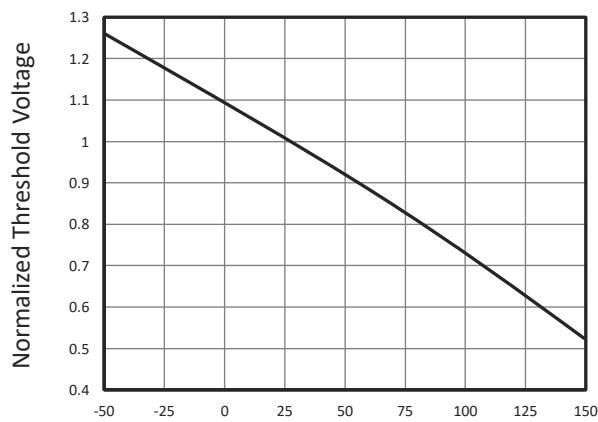
Id-Drain Current (A)  
**Drain-Source On Resistance**



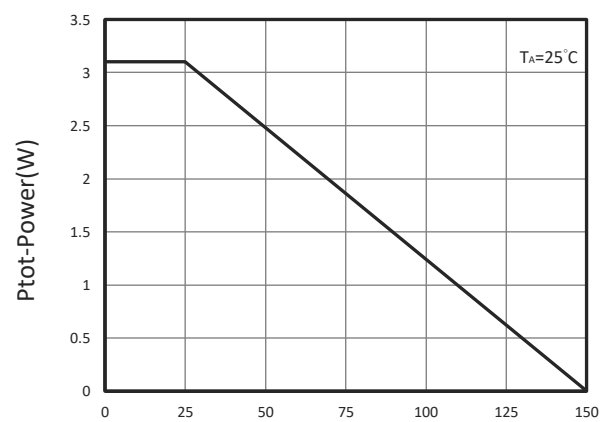
Qg-Gate Charge (nC)  
**Gate Charge**



VDS-Drain Source Voltage (V)  
**Capacitance**

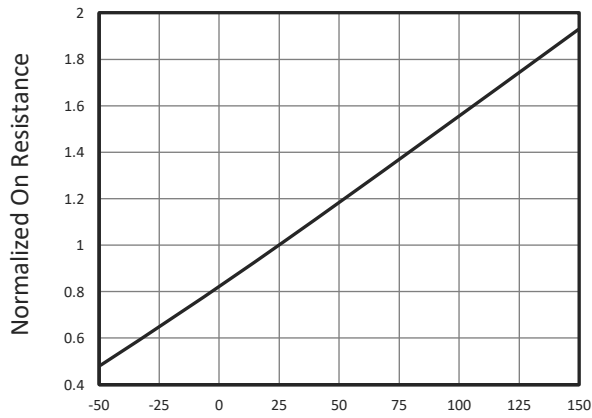


TJ-Junction Temperature (°C)  
**Gate Threshold Voltage**

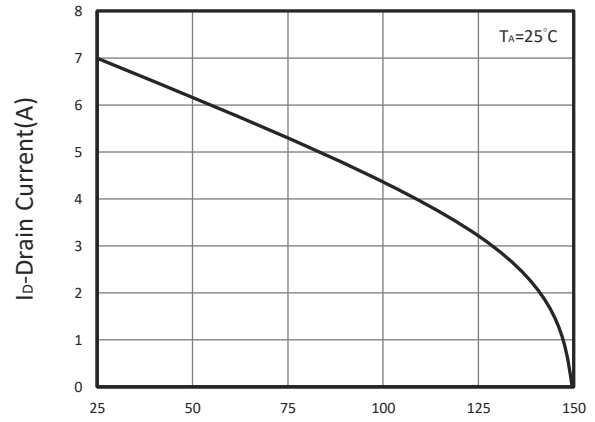


TJ-Junction Temperature (°C)  
**Power Dissipation**

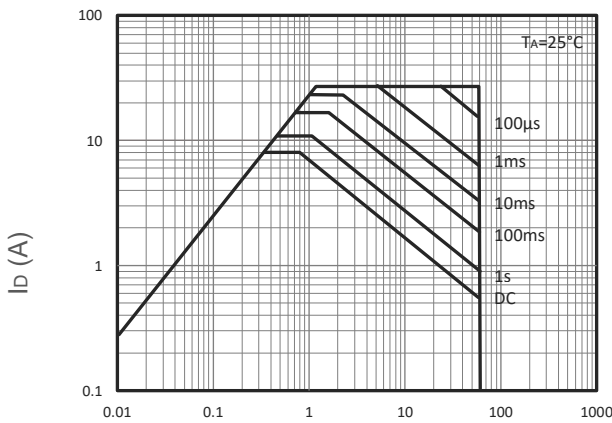
**TYPICAL CHARACTERISTICS**



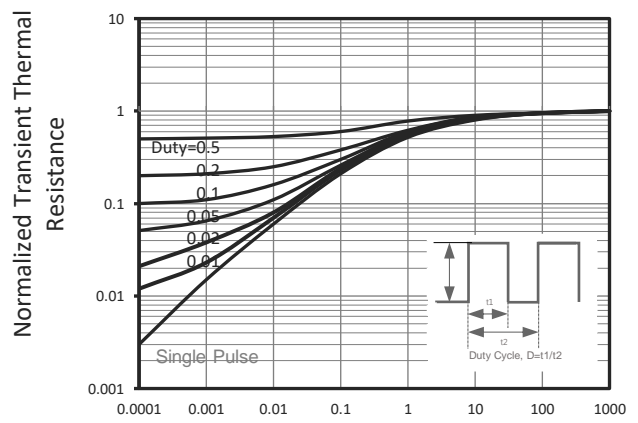
**$R_{DS(ON)}$  vs Junction Temperature**



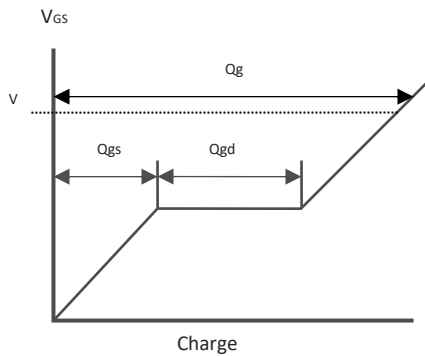
**Drain Current vs Tc**



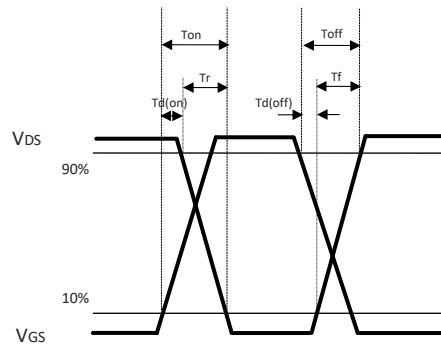
**Maximum Safe Operation Area**



**Thermal Transient Impedance**

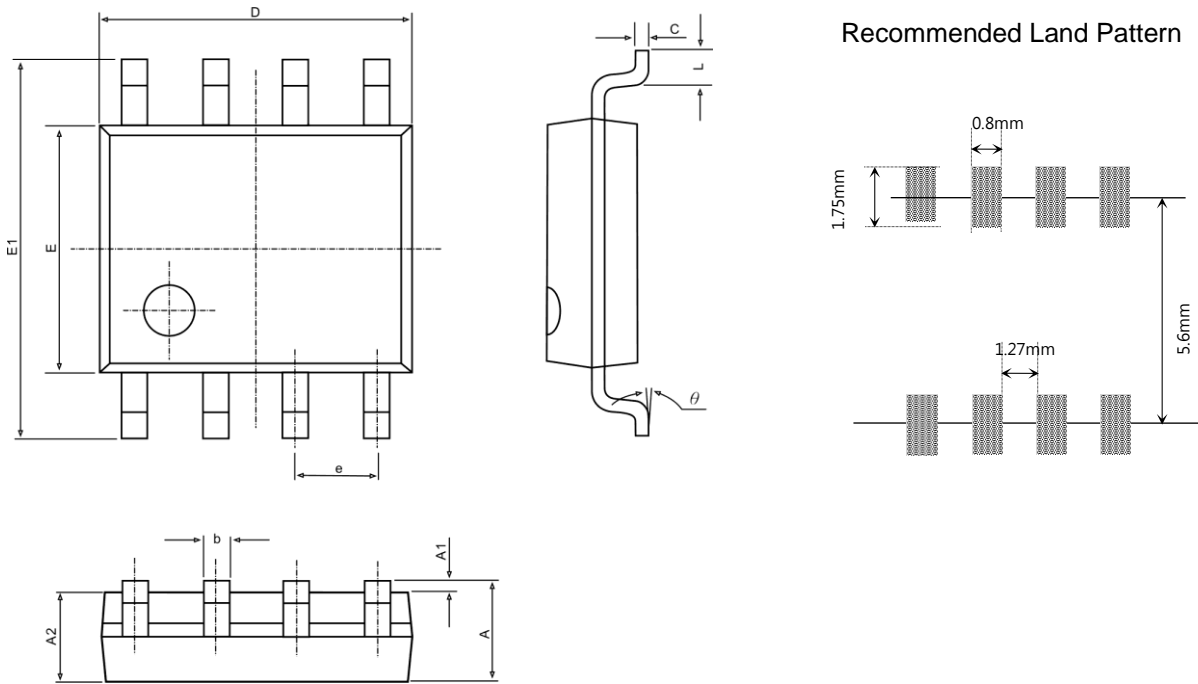


**Gate Charge Waveform**



**Switching Time Waveform**

## ■ SOP-8 PACKAGE DIMENSIONS



| Symbol | Dimensions In Millimeters |       | Dimensions In Inches |       |
|--------|---------------------------|-------|----------------------|-------|
|        | Min.                      | Max.  | Min.                 | Max.  |
| A      | 1.350                     | 1.750 | 0.053                | 0.069 |
| A1     | 0.100                     | 0.250 | 0.040.               | 0.010 |
| A2     | 1.350                     | 1.550 | 0.053                | 0.061 |
| b      | 0.330                     | 0.510 | 0.130                | 0.020 |
| c      | 0.170                     | 0.250 | 0.006                | 0.010 |
| D      | 4.700                     | 5.100 | 0.185                | 0.200 |
| E      | 3.800                     | 4.000 | 0.150                | 0.157 |
| E1     | 5.800                     | 6.200 | 0.228                | 0.244 |
| e      | 1.270BSC.                 |       | 0.050BSC.            |       |
| L      | 0.400                     | 1.270 | 0.016                | 0.005 |
| θ      | 0°                        | 8°    | 0°                   | 8°    |